Platamid® HX 2620 Powder

PA*

ARKEMA

Product Texts

Platamid® HX 2620 Powder

Copolyamide Hot Melt Adhesive / Textile Applications

Platamid® HX 2620 Powder is a low melt viscosity copolyamide adhesive powder for the production of fusible interlinings.
Platamid® HX 2620 Powder offers good laundry resistance and good steam resistance at low/medium fusing conditions.

AVAILABLE GRADES

This grade is available in different grain sizes:

- Platamid® HX 2620 PA80 (0-80 µm paste dot)

- Platamid® HX 2620 PRA 170 (0-170 µm double dot)

PACKAGING

- Platamid® HX 2620 PA80 and Platamid® HX 2620 PRA 170 are delivered in 20 kg sealed bags.

SHELF LIFE

Two years from the date of delivery. For any use above this limit, please refer to our technical services.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
[C] Melt volume-flow rate, MVR	**41.5 / ***	cm³/10min	ISO 1133
Temperature	**150 / ***	°C	-
Load	**2.16 / ***	kg	-

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
[C] Melting temperature, 10°C/min	**124 / ***	°C	ISO 11357-1/-3

[C]: CAMPUS

Characteristics

Delivery form

Powder

Features

Copolymer

Regional Availability

North America, Europe, Asia Pacific, South and Central America, Near East/Africa